

Peltron[®]

Product Name	XJS-3050
Product Category	Conductive Adhesive
Use	Semiconductor Modules, Car Electro Devices, General Modules, Die Attach, Touch Panel, Solar Battery
Function	One Component Type, Low Temperature Curing

Item	Condition	Unit	Typical Value
General Item			
Package	-	-	Pot, Syringe
Liquid Feature			
Viscosity	B type viscometer / 10rpm / @25°C	Pa·s	60
Storage stability	Unopen / Frozen (below -15°C)	-	2 months
Cured Properties			
Recommended Curing Condition	Heat air circulation oven	-	100°C x 60 minutes
Volume Resistivity	100°C x 60 minutes cure	$\Omega \cdot \text{cm}$	4.5×10^{-4}
Shear Adhesive Strength @25°C	4mm ² Si chip/Cu plated surface	N/mm^2	22
	4mm ² Si chip/Fe surface		27
Characteristics	Low temperature curable conductive adhesive High adhesive strength to Cu		

The above values are reference and not specification.



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